

SuperFET**

FCP16N60 / FCPF16N60

600V N-Channel MOSFET

Features

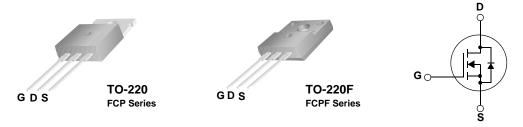
- 650V @T_J = 150°C
- Typ. $R_{ds(on)} = 0.22\Omega$
- Ultra low gate charge (typ. Qg=55nC)
- Low effective output capacitance (typ. Coss.eff=110pF)
- 100% avalanche tested
- RoHS Compliant



Description

SuperFETTM is, Fairchild's proprietary, new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy. Consequently, SuperFET is very suitable for various AC/DC power conversion in switching mode operation for system miniaturization and higher efficiency.



Absolute Maximum Ratings

Symbol	Parameter		FCP16N60	FCPF16N60	Unit	
V _{DSS}	Drain-Source Voltage		600		V	
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		16 10.1	16* 10.1*	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	48	48*	Α
V _{GSS}	Gate-Source voltage		± 30		V	
E _{AS}	Single Pulsed Avalanche Energy ((Note 2)	450		mJ
I _{AR}	Avalanche Current		(Note 1)	16		А
E _{AR}	Repetitive Avalanche Energy		(Note 1)	20.8		mJ
dv/dt	Peak Diode Recovery dv/dt ((Note 3)	4.5		V/ns
P_D	Power Dissipation	(T _C = 25°C) - Derate above 25°C		167 1.33	37.9 0.3	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C	
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300		°C	

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FCP16N60	FCPF16N60	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.75	3.3	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/W	

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FCP16N60	FCP16N60	TO-220	-	-	50
FCPF16N60	FCPF16N60	TO-220F	-	=	50

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Off Charac	teristics			•	•	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^{\circ}C$	600			V
		$V_{GS} = 0V, I_D = 250\mu A, T_J = 150^{\circ}C$		650		V
ΔBV_{DSS} / ΔT_{J}	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C		0.6		V/°C
BV _{DSS}	Drain-Source Avalanche Breakdown Voltage	V _{GS} = 0V, I _D = 16A		700		V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600V, V_{GS} = 0V$ $V_{DS} = 480V, T_{C} = 125^{\circ}C$			1 10	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	$V_{GS} = 30V$, $V_{DS} = 0V$			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -30V$, $V_{DS} = 0V$			-100	nA
On Charac	teristics			•	•	
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 8A		0.22	0.26	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40V$, $I_D = 8A$ (Note 4)		11.5		S
Dynamic C	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 25V, V_{GS} = 0V,$		1730	2250	pF
C _{oss}	Output Capacitance	f = 1.0MHz		960	1150	pF
C _{rss}	Reverse Transfer Capacitance			85		pF
C _{oss}	Output Capacitance	V _{DS} = 480V, V _{GS} = 0V, f = 1.0MHz		45	60	pF
C _{oss} eff.	Effective Output Capacitance	Output Capacitance $V_{DS} = 0V$ to 400V, $V_{GS} = 0V$		110		pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 300V, I _D = 16A		42	85	ns
t _r	Turn-On Rise Time	$R_G = 25\Omega$		130	270	ns
t _{d(off)}	Turn-Off Delay Time			165	340	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		90	190	ns
Qg	Total Gate Charge	V _{DS} = 480V, I _D = 16A		55	70	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10V		10.5	13	nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		28		nC
Drain-Sour	ce Diode Characteristics and Maximur	n Ratings			•	•
I _S	Maximum Continuous Drain-Source Dio	de Forward Current			16	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				48	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S =16A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 16A		435		ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s (Note 4)$		7.0		μС

NOTES:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. I $_{AS}$ = 8A, V $_{DD}$ = 50V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25°C
- 3. $I_{SD} \leq$ 16A, di/dt \leq 200A/ μ s, $V_{DD} \leq$ BV $_{DSS}$, Starting T $_{J}$ = 25°C
- 4. Pulse Test: Pulse width $\leq 300 \mu \text{s}, \, \text{Duty Cycle} \leq 2\%$
- 5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

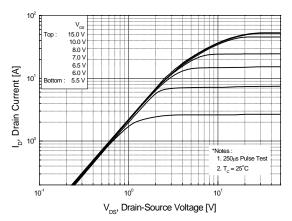


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

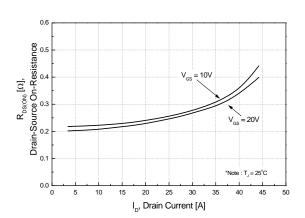


Figure 5. Capacitance Characteristics

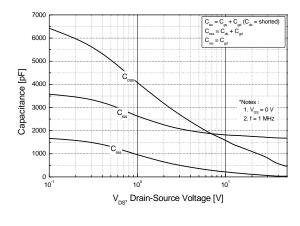


Figure 2. Transfer Characteristics

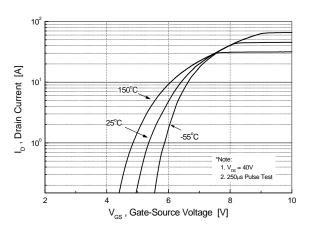


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

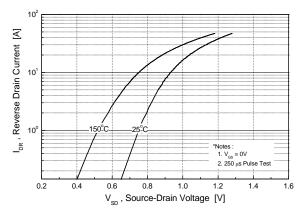
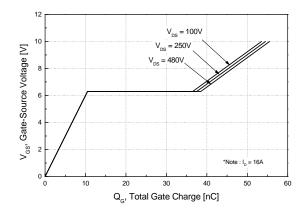


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

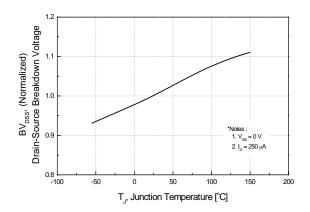


Figure 8. On-Resistance Variation vs. Temperature

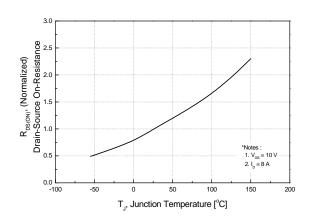


Figure 9-1. Maximum Safe Operating Area for FCP16N60

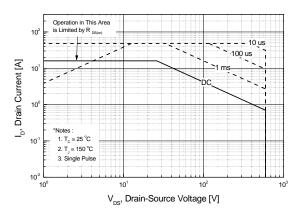


Figure 9-2. Maximum Safe Operating Area for FCPF16N60

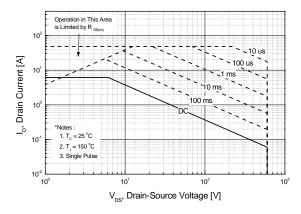


Figure 10. Maximum Drain Current vs. Case Temperature

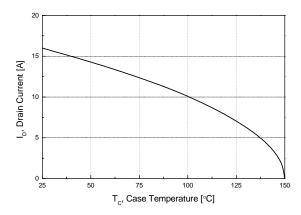


Figure 11-1. Transient Thermal Response Curve (FCP16N60)

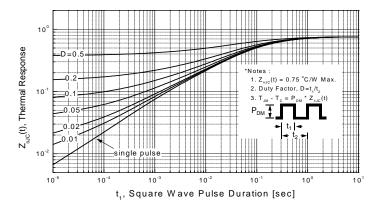
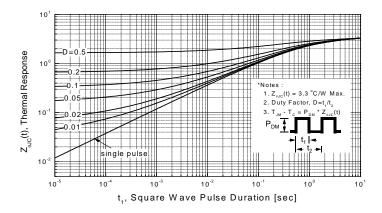
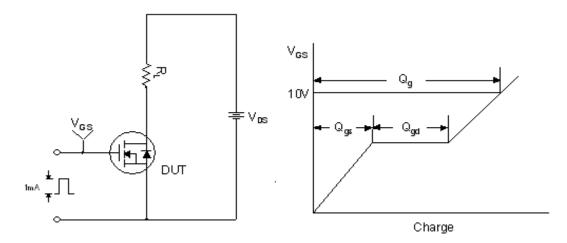


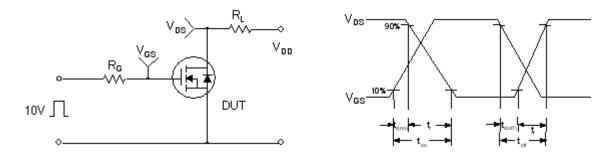
Figure 11-2. Transient Thermal Response Curve (FCPF16N60)



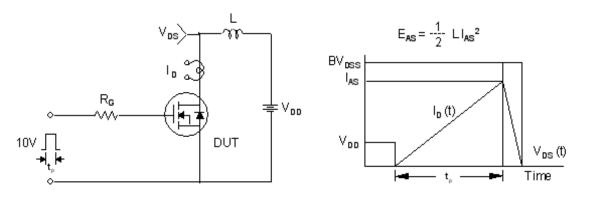
Gate Charge Test Circuit & Waveform



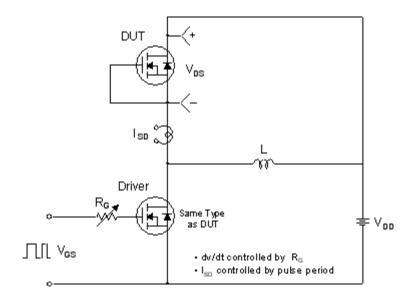
Resistive Switching Test Circuit & Waveforms

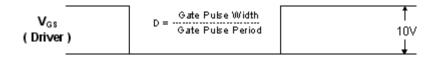


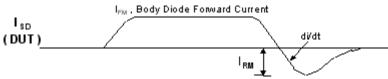
Unclamped Inductive Switching Test Circuit & Waveforms



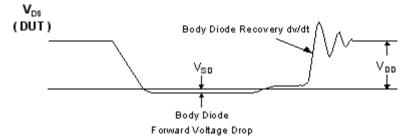
Peak Diode Recovery dv/dt Test Circuit & Waveforms





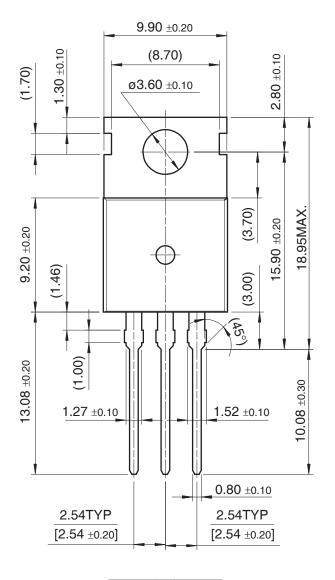


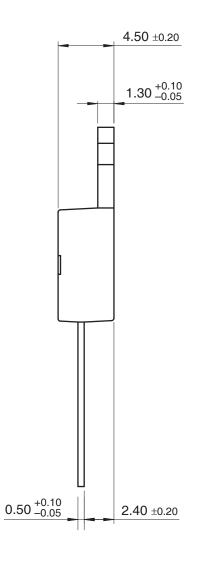
Body Diode Reverse Current



Mechanical Dimensions

TO-220



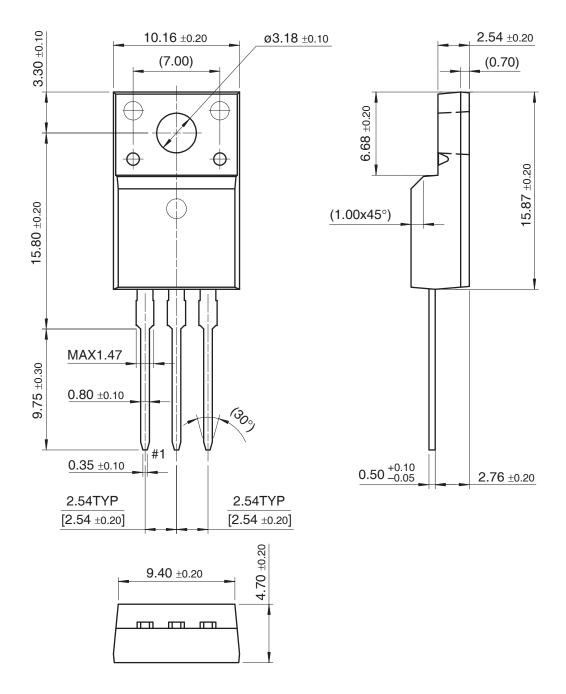


10.00 ±0.20

Dimensions in Millimeters

Mechanical Dimensions (Continued)

TO-220F



Dimensions in Millimeters





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